

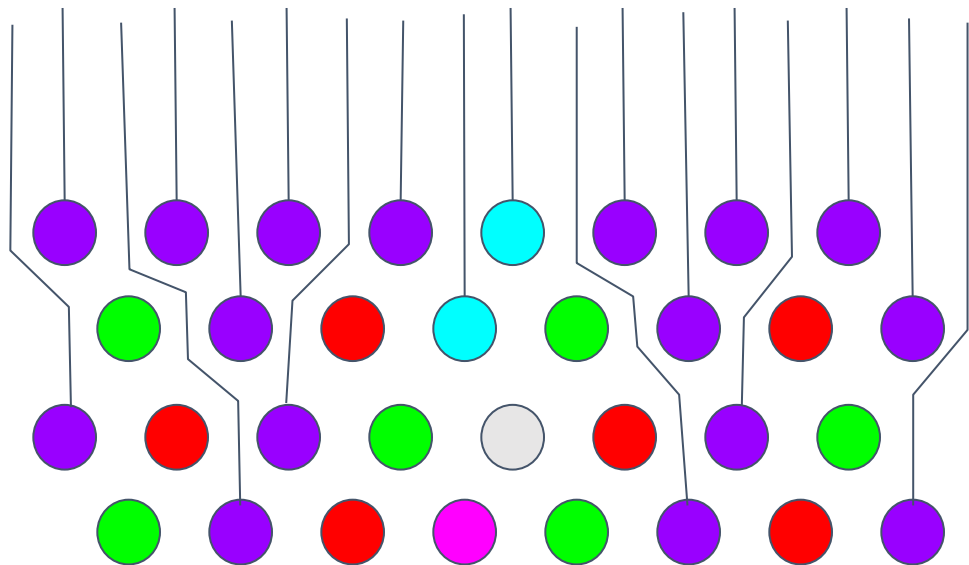


BW, Routing, Stack Up, Silicon Area

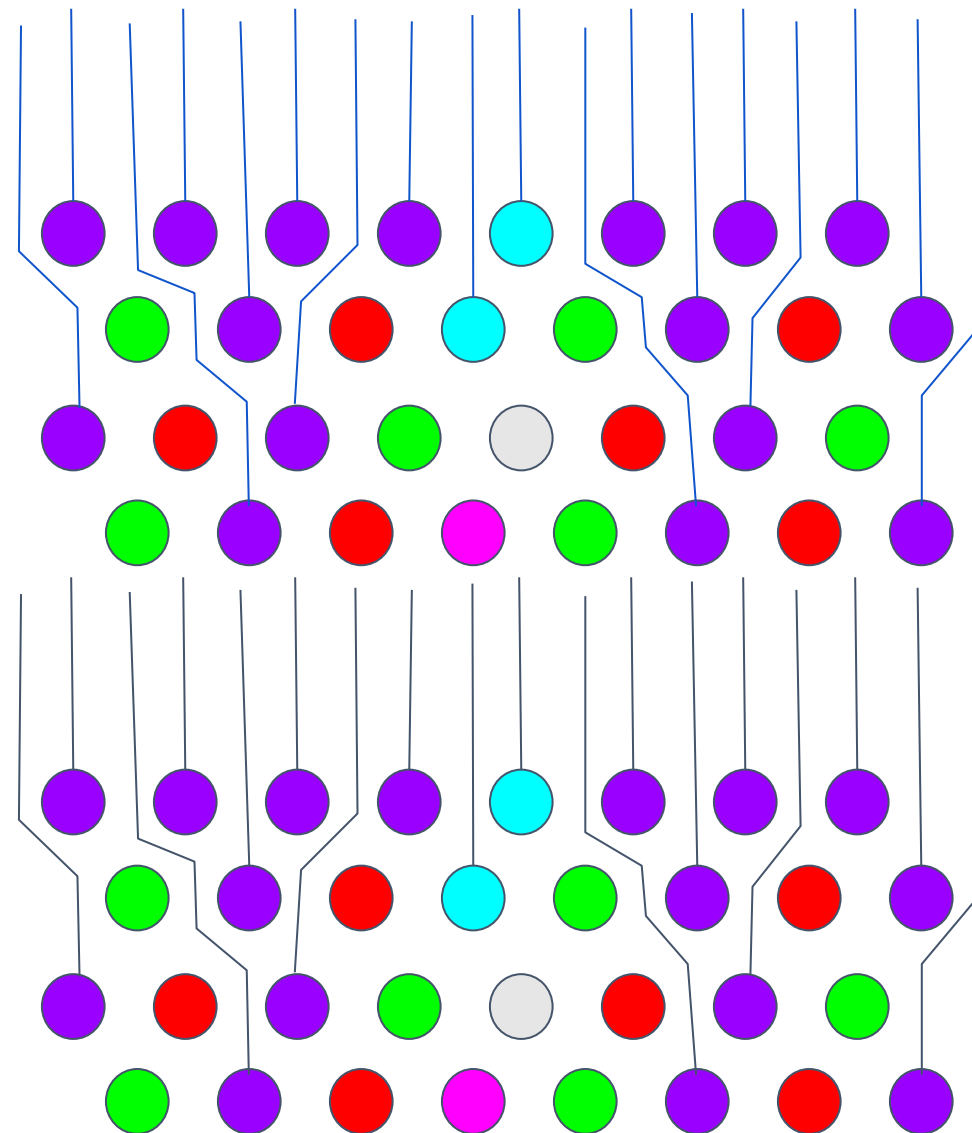
Feb 25th, 2020

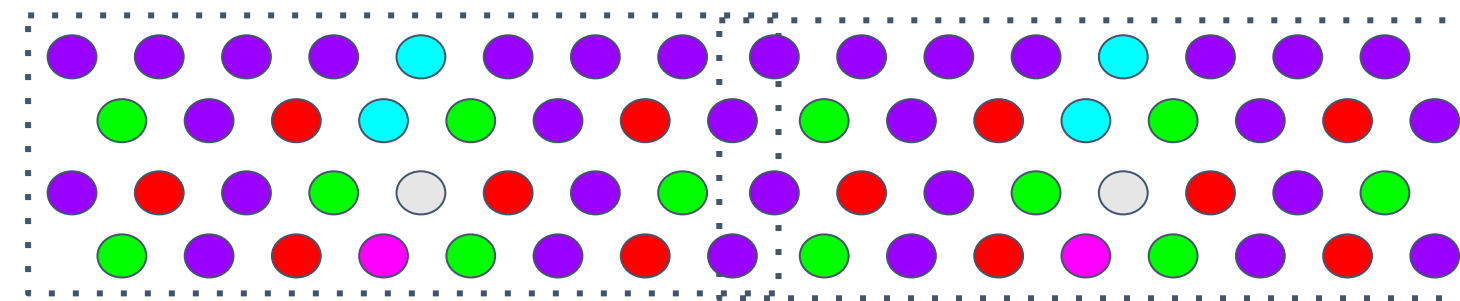
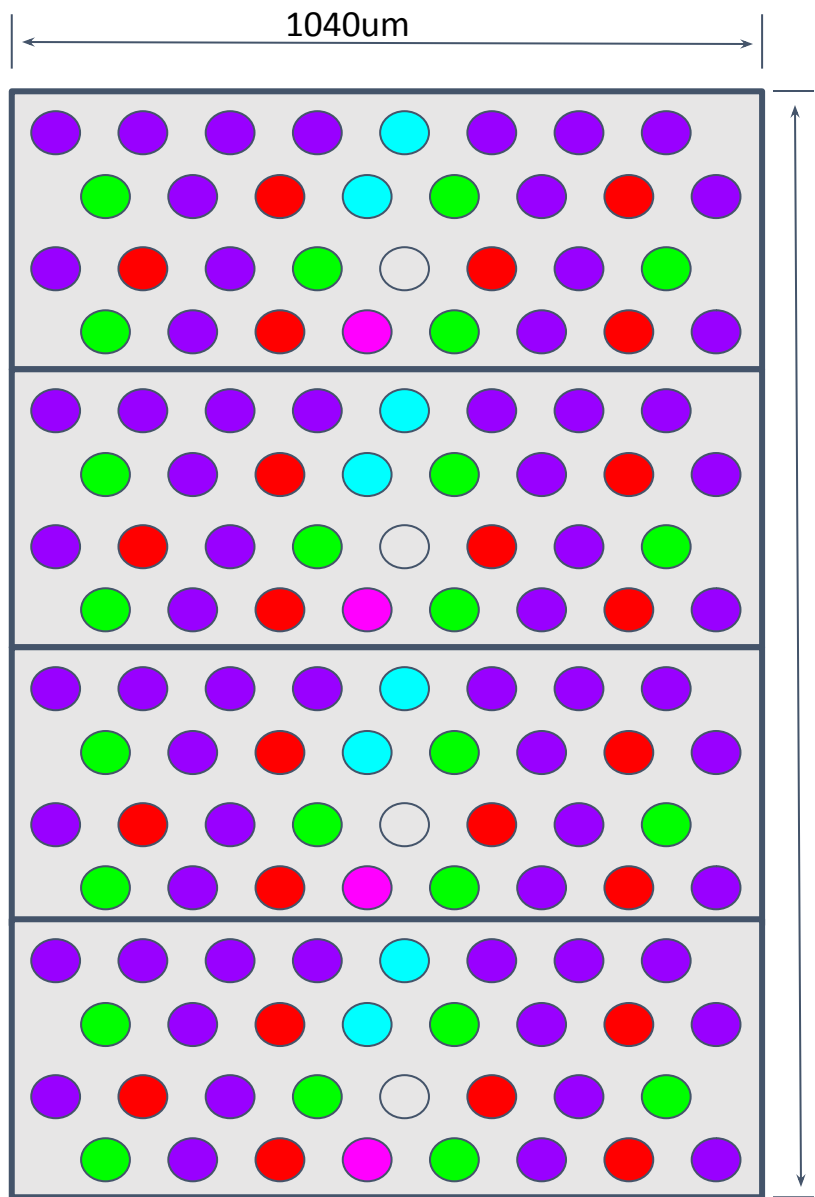
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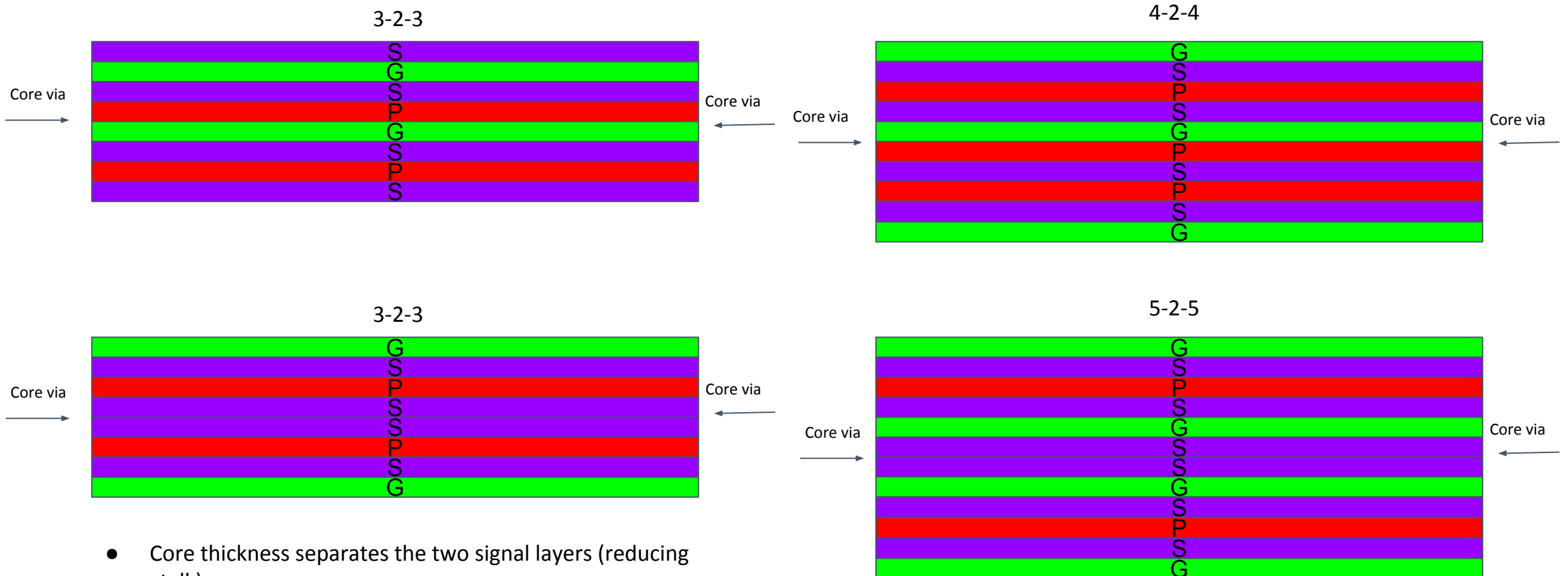


1	3	5	7	C	9	1 ₁	1 ₃
	g	4	p	C	g	1 ₀	p 1 ₅
0	p	6	g	R	p	1 ₂	g
	g	2	p	F	g	8	p 1 ₅





Organic Substrate Stack Up Options



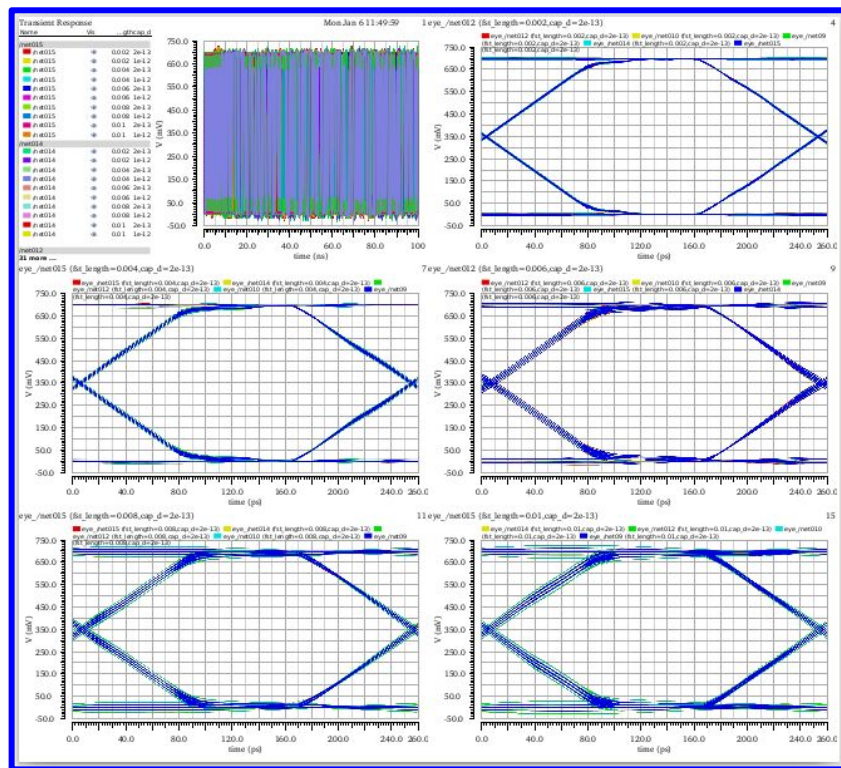
- Core thickness separates the two signal layers (reducing xtalk)
- Any routing layers on the bottom will perform worse than on the top (via down through core vias and back up through core vias)

BW, Routing Layers, Silicon Area

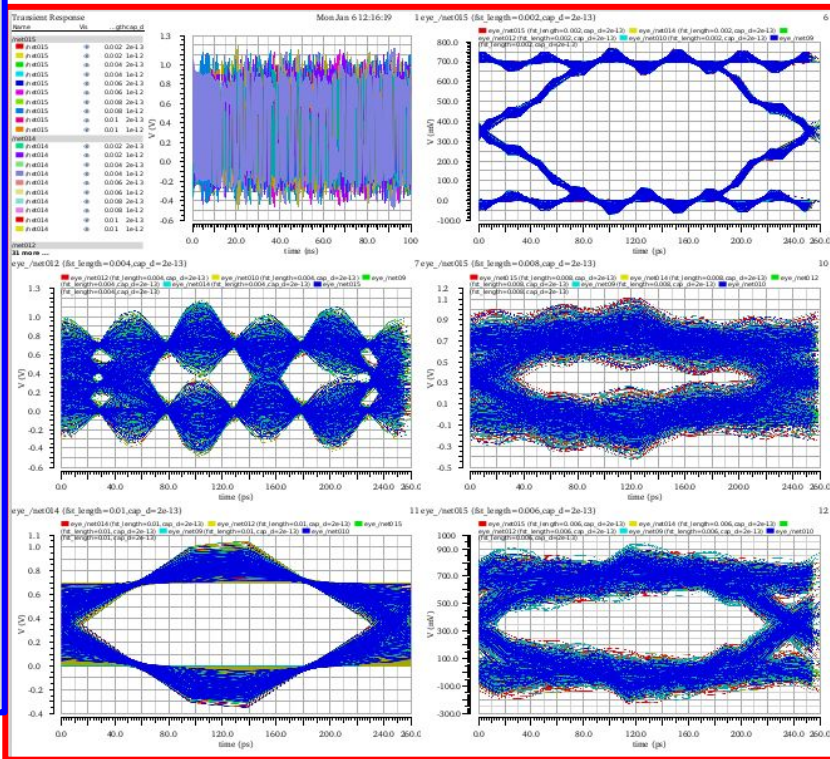
# of lanes/layer	16	16	16	16
# of routing layers	1	2	3	4
# of slices	5	5	5	5
Max DDR speed (Gb/s)	4	4	4	4
Total Bandwidth(Gb/s)	320	640	960	1280
Total Bandwidth (GB/s)	40	80	120	160
Pacakge Stack Up	2-2-2	3-2-3	3-2-3	4-2-4
Area per 16 lanes				
W (um)	1040			
L (um)	426.75			
x pitch (um)	130			
y pitch (um)	106.68			
Total Silicon Area (sq.mm)	2.2191	4.4382	6.6573	8.8764
W (um)	5.2	5.2	5.2	5.2
L(um)	0.42675	0.8535	1.28025	1.707

16	16	16	16	16	L1
16	16	16	16	16	L2
16	16	16	16	16	L3
16	16	16	16	16	L4
Stack 4	Stack 3	Stack 2	Stack 1	Stack 0	
Link					
16	Slice				

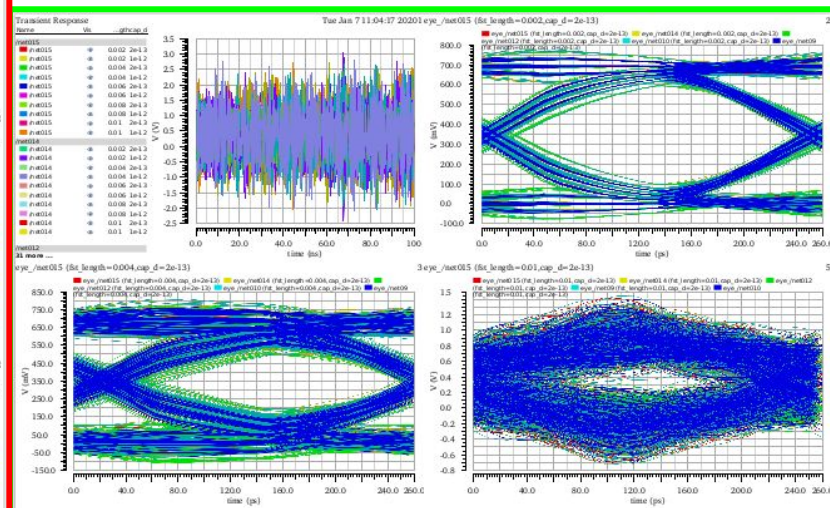
Driver + Channel - What If Analysis



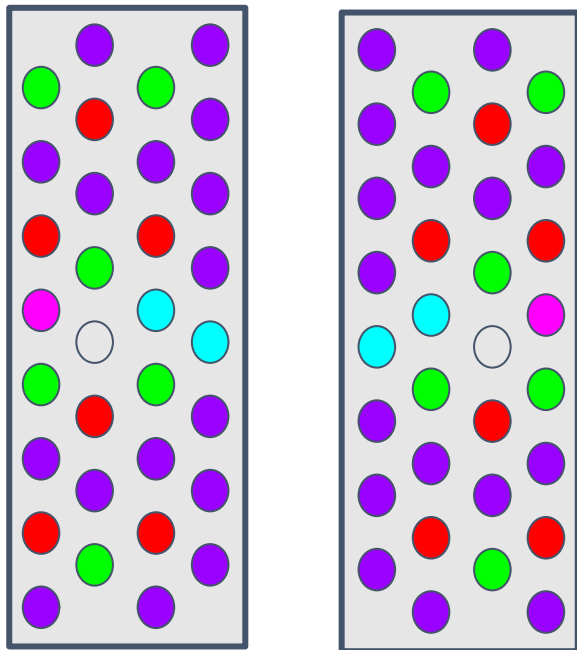
Termination + Various Channel Lengths
[2mm-10mm]
BW Target (4Gb/s DDR)
Organic Substrate (GX92 material, 25/25)



No Termination + Various Channel Lengths
[2mm-10mm]
BW Target (4Gb/s DDR)
Organic Substrate (GX92 material, 25/25)

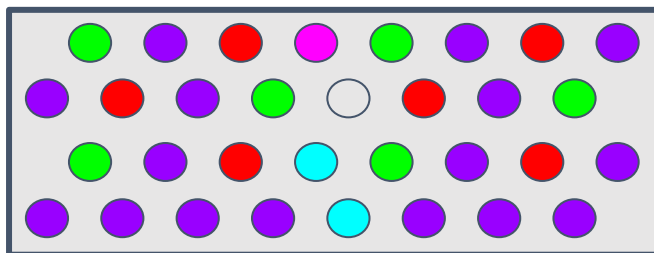


No Termination + Various Channel Lengths
[2mm-10mm] + **Receiver Capacitance**
BW Target (4Gb/s DDR)
Organic Substrate (GX92 material, 25/25)

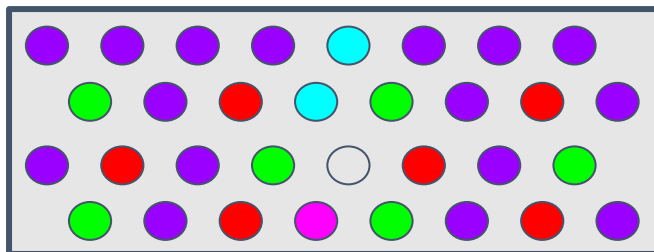


Tx

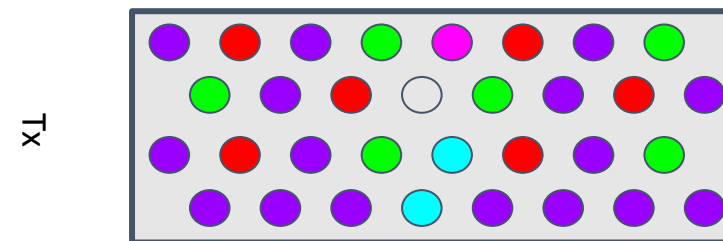
Rx



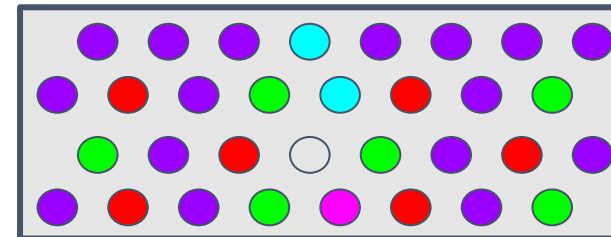
Rx



Tx



Tx



Rx

Rx

Tx

